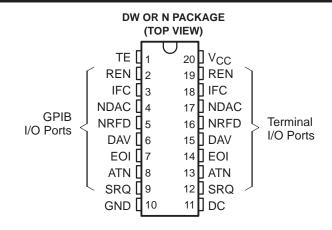
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- Suitable for IEEE Standard 488-1978 (GPIB)
- 8-Channel Bidirectional Transceivers
- Designed to Implement Control Bus Interface
- Designed for Single Controller
- High-Speed Advanced Low-Power Schottky Circuitry
- Low Power Dissipation . . . 46 mW Max Per Channel
- Fast Propagation Times . . . 20 ns Max
- High-Impedance pnp Inputs
- Receiver Hysteresis . . . 650 mV Typ
- Bus-Terminating Resistors Provided on Driver Outputs
- No Loading of Bus When Device Is Powered Down (V_{CC} = 0)
- Power-Up/Power-Down Protection (Glitch Free)

description/ordering information

The SN75ALS161 eight-channel general-purpose interface bus transceivers are high-speed, advanced low-power Schottky-process devices designed to provide the



CHANNEL-IDENTIFICATION TABLE

NAME	IDENTITY	CLASS
DC	Direction Control	Control
TE	Talk Enable	Control
ATN	Attention	
SRQ	Service Request	
REN	Remote Enable	Bus
IFC	Interface Clear	Management
EOI	End or Identify	
DAV	Data Valid	5.
NDAC	Not Data Accepted	Data Transfer
NRFD	Not Ready for Data	i i ansiei

bus-management and data-transfer signals between operating units of a single-controller instrumentation system. When combined with the SN75ALS160 octal bus transceivers, this device provides a complete 16-wire interface for the IEEE 488 bus.

The SN75ALS161 device features eight driver-receiver pairs connected in a front-to-back configuration to form input/output (I/O) ports at both the bus and terminal sides. The direction of data through these driver-receiver pairs is determined by the direction-control (DC) and talk-enable (TE) signals.

The driver outputs general-purpose interface bus (GPIB I/O ports) feature active bus-terminating resistor circuits designed to provide a high impedance to the bus when $V_{CC} = 0$. The drivers are designed to handle sink-current loads up to 48 mA. Each receiver features pnp transistor inputs for high input impedance and hysteresis of 400 mV on the commercial part, and 250 mV on the military part, minimum, for increased noise immunity. All receivers have 3-state outputs, to present a high impedance to the terminal when disabled.

The SN75ALS161 is characterized for operation from 0°C to 70°C.

ORDERING INFORMATION

T _A PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	PDIP (N)	Tube of 20	SN75ALS161N	SN75ALS161N	
0°C to 70°C	0010 (011)	Tube of 25	SN75ALS161DW	7541.0404	
	SOIC (DW)	Reel of 2000	SN75ALS161DWR	75ALS161	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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FUNCTION TABLE RECEIVE/TRANSMIT

C	ONTRO	LS	BUS	-MANA	SEMENT	CHANN	IELS	DATA-TRANSFER CHANNELS			
DC	TE	ATN†	ATN [†] (CO	SRQ NTROLI	REN LED BY	IFC DC)	EOI	DAV (CON	NDAC TROLLED E	NRFD BY TE)	
Н	Н	Н	,	_	,	,	Т	-	_	-	
Н	Н	L	R	ı	R	R	R	ı	R	R	
L	L	Н	_		_	_	R	-	-	_	
L	L	L	l '	R	1	1	Т	R	ı	ı	
Н	L	Х	R	Т	R	R	R	R	Т	Т	
L	Н	Χ	Т	R	Т	Т	T	Т	R	R	

H = high level, L = low level, R = receive, T = transmit, X = irrelevant

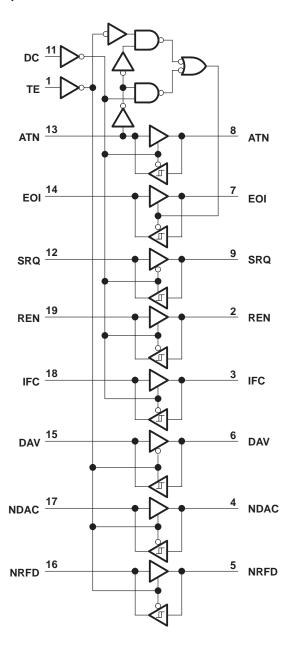
Direction of data transmission is from the terminal side to the bus side, and the direction of data receiving is from the bus side to the terminal side.

Data transfer is noninverting in both directions.



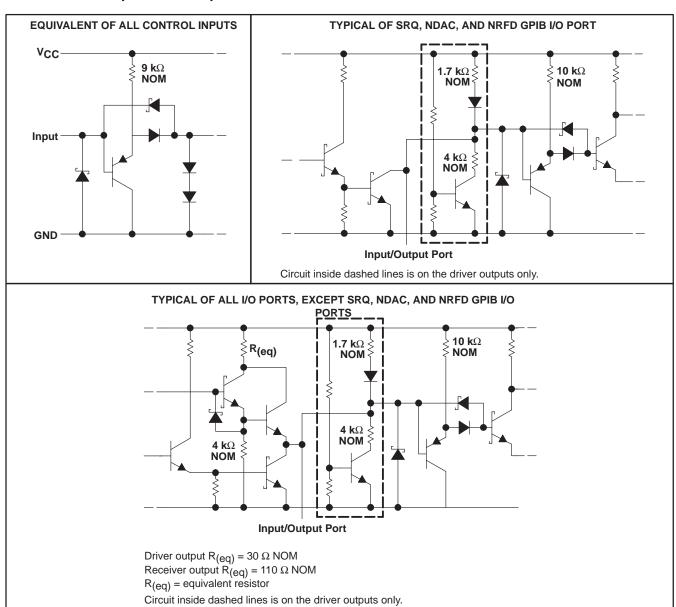
[†] ATN is a normal transceiver channel that functions additionally as an internal direction control or talk enable for EOI whenever the DC and TE inputs are in the same state. When DC and TE are in opposite states, the ATN channel functions as an independent transceiver only.

logic diagram (positive logic)



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schematics of inputs and outputs



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)		7 V
Input voltage, V _I		
Low-level driver output current, I _{OL}	1	100 mA
Package thermal impedance, θ_{JA} (see Notes 2 and 3):	: DW package 5	58°C/W
	N package 6	39°C/W
Operating virtual junction temperature, T _J		150°C
Storage temperature range, T _{sto}	–65°C to	150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to network ground terminal.
 - 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.75	5	5.25	V
VIH	High-level input voltage		2			V
VIL	Low-level input voltage				8.0	V
	I Park Town London London	Bus ports with pullups active			- 5.2	mA
ЮН	High-level output current	Terminal ports			- 800	μΑ
		Bus ports			48	
IOL	Low-level output current	Terminal ports			16	mA
TA	Operating free-air temperature		0		70	°C

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electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER		TES	T CONDITION:	s†	MIN	TYP‡	MAX	UNIT
٧ıK	Input clamp voltage		$I_{I} = -18 \text{ mA}$				-0.8	-1.5	V
V _{hys}	Hysteresis voltage (V _{IT+} – V _{IT-})	Bus				0.4	0.65		V
		Terminal	I _{OH} = - 800 μA,	V _{CC} = MIN	T _A = 25°C and MAX	2.7	3.5		
., 8	LPak lavel extend value				$T_A = MIN$	2.7	3.5		V
V _{OH} §	High-level output voltage	Bus	I _{OH} = - 5.2 mA,	V _{CC} = MIN	T _A = 25°C and MAX	2.2			v
				$T_A = MI$		2.2			
V	Low-level output voltage	Terminal	$I_{OL} = 16 \text{ mA},$	$V_{CC} = MIN$			0.3	0.5	V
VOL	Low-level output voltage	Bus	$I_{OL} = 48 \text{ mA},$	$V_{CC} = MIN$			0.35	0.5	V
lį	Input current at maximum input voltage	Terminal	V _I = 5.5 V,	$V_{CC} = MAX$			0.2	100	μΑ
lн	High-level input current	Terminal and control inputs	V _I = 2.7 V,	V _{CC} = MAX			0.1	20	μΑ
			$I_{I(bus)} = 0$			2.5	3	3.7	
V _{I/O}	Voltage at GPIB I/O port		$I_{I(bus)} = 0$			2.5	3	3.7	V
			$I_{I(bus)} = -12 \text{ mA}$	l				-1.5	
I _{IL}	Low-level input current	Terminal and control inputs	V _I = 0.5 V,	V _{CC} = MAX			-10	-100	μΑ
			$V_{I(bus)} = -1.5 V$	to 0.4 V		-1.3			
			$V_{I(bus)} = 0.4 V t$	o 2.5 V		0		-3.2	
I _{I/O}	Current into GPIB I/O port	Power on	$V_{I(bus)} = 2.5 V t$	o 3.7 V				2.5 -3.2	mA
	·		$V_{I(bus)} = 3.7 V t$	o 5 V		0		2.5	
			$V_{I(bus)} = 5 V to$	5.5 V		0.7		2.5	
		Power off	VCC = 0	$V_{I(bus)} = 0 to$	o 2.5 V			40	μΑ
8	Short-circuit output current	Terminal	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\			-15	-35	-75	mA
los§	Short-Groun output current	Bus	V _{CC} = MAX			-25	-50	-125	IIIA
ICC	Supply current		No load,	TE and DC lo			55	75	mA
C _{I/O}	GPIB I/O port capacitance		$V_{CC} = 0 \text{ to 5 V},$	$V_{I/O} = 0 \text{ to } 2$	V, f = 1 MHz		30		pF

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

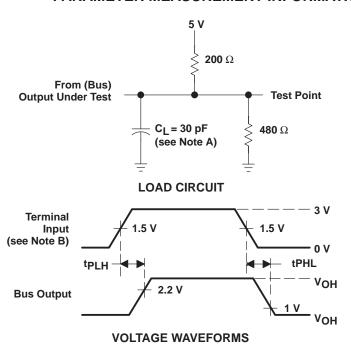
[‡] All typical values are at $V_{CC} = 5$ V, $T_A = 25^{\circ}$ C. § V_{OH} and I_{OS} apply to 3-state outputs only.

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switching characteristics over recommended operating free-air temperature range, $V_{CC} = 5 \text{ V}$

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
^t PLH	Propagation delay time, low- to high-level output	Terminal	Bus	C _I = 30 pF,		10	20	ns
^t PHL	Propagation delay time, high- to low-level output	Terminal	Bus	See Figure 1		12	20	110
tPLH	Propagation delay time, low- to high-level output		-	C _L = 30 pF,		5	10	
tPHL	Propagation delay time, high- to low-level output	Bus	Terminal	See Figure 2		7	14	ns
^t PZH	Output enable time to high level		Bus (ATN, EOI,				30	
^t PHZ	Output disable time from high level	TE -: DC		$C_{I} = 15 pF,$			20	
tPZL	Output enable time to low level	TE or DC	REN, IFC, and DAV)	See Figure 3			45	ns
t _{PLZ}	Output disable time from low level		,				20	
^t PZH	Output enable time to high level						30	
^t PHZ	Output disable time from high level	TE or DC	Terminal	C _L = 15 pF,			25	20
tpzL	Output enable time to low level	TEULDO	remina	See Figure 4			30	ns
tPLZ	Output disable time from low level						25	

[†] All typical values are at $T_A = 25$ °C.

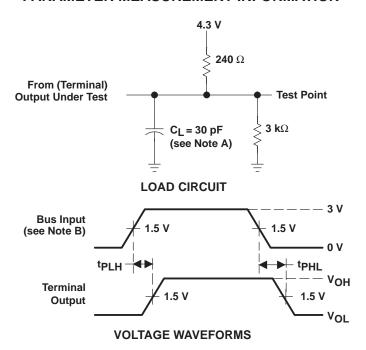


NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_{\Gamma} \leq$

Figure 1. Terminal-to-Bus Load Circuit and Voltage Waveforms

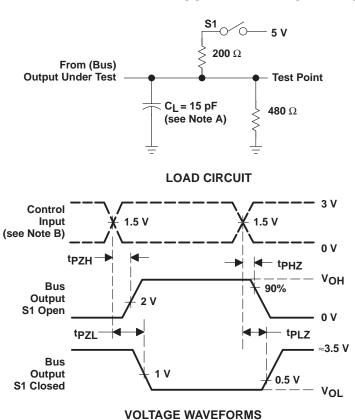




NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_{\Gamma} \leq$

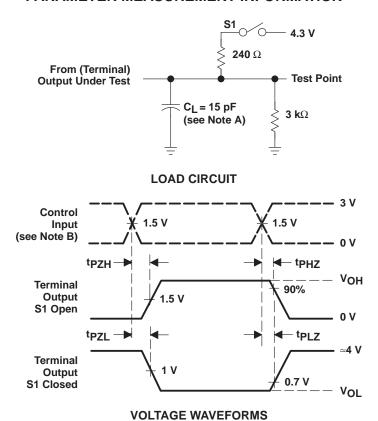
Figure 2. Bus-to-Terminal Load Circuit and Voltage Waveforms



NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_r \leq$ 6 ns, $t_f \leq$ 6 ns, $Z_O = 50 \Omega$.

Figure 3. Bus Load Circuit and Voltage Waveforms

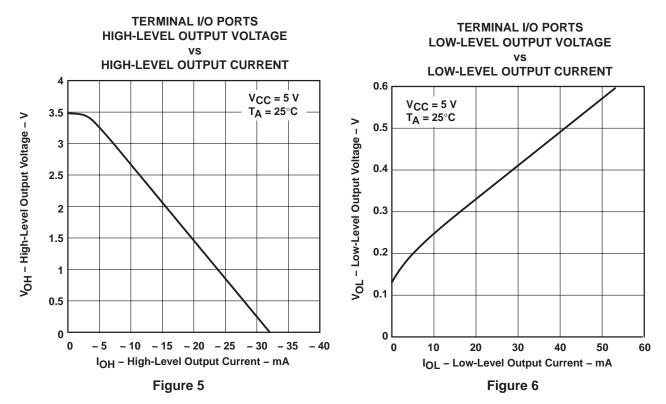


NOTES: A. C_L includes probe and jig capacitance.

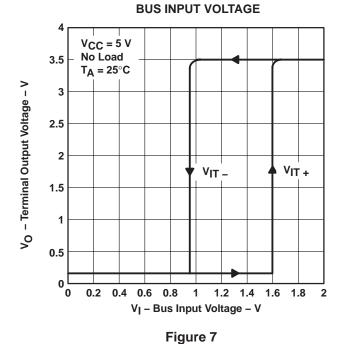
B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{f} \leq$ 6 ns, $t_{Q} =$ 50 Ω .

Figure 4. Terminal Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS[†]



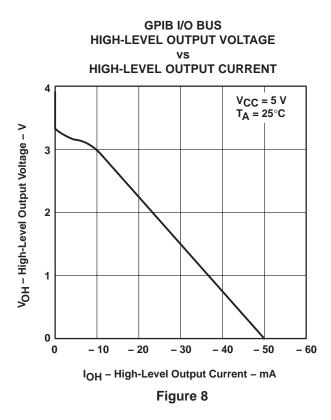
TERMINAL OUTPUT VOLTAGE vs

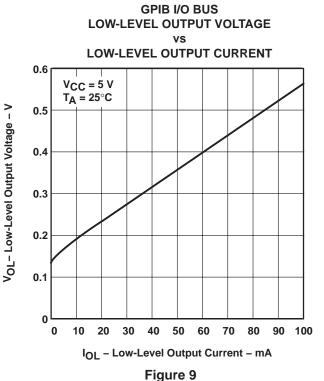


† Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



TYPICAL CHARACTERISTICS[†]





GPIB I/O BUS

BUS OUTPUT VOLTAGE
vs
TERMINAL INPUT VOLTAGE

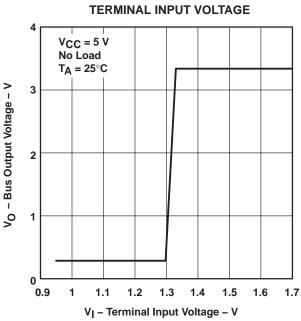
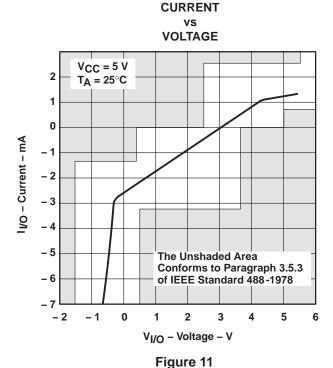


Figure 10



† Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN75ALS161DW	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS161
SN75ALS161DW.A	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS161
SN75ALS161DWG4	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS161
SN75ALS161DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS161
SN75ALS161DWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS161
SN75ALS161N	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN75ALS161N
SN75ALS161N.A	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN75ALS161N

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF SN75ALS161:

Military: SN55ALS161

NOTE: Qualified Version Definitions:

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS161DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

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*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
I	SN75ALS161DWR	SOIC	DW	20	2000	350.0	350.0	43.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN75ALS161DW	DW	SOIC	20	25	506.98	12.7	4826	6.6
SN75ALS161DW.A	DW	SOIC	20	25	506.98	12.7	4826	6.6
SN75ALS161DWG4	DW	SOIC	20	25	506.98	12.7	4826	6.6
SN75ALS161N	N	PDIP	20	20	506	13.97	11230	4.32
SN75ALS161N.A	N	PDIP	20	20	506	13.97	11230	4.32

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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